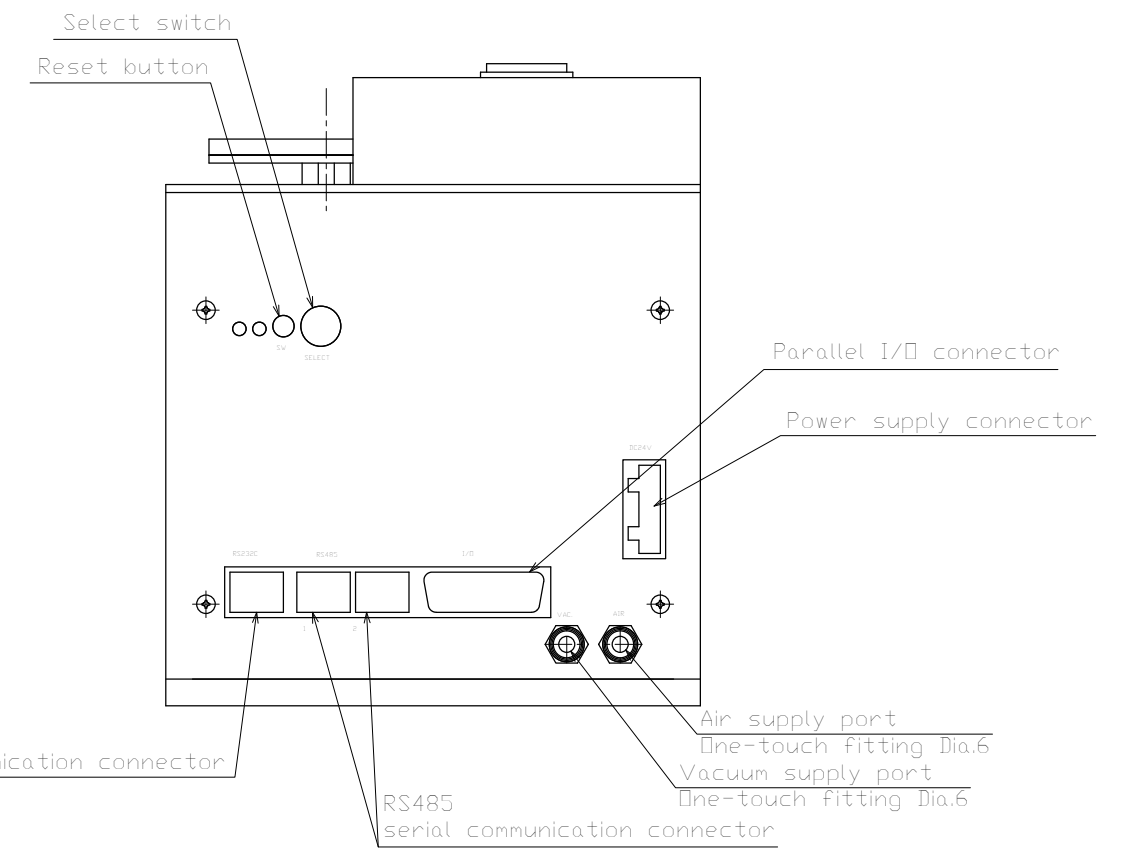
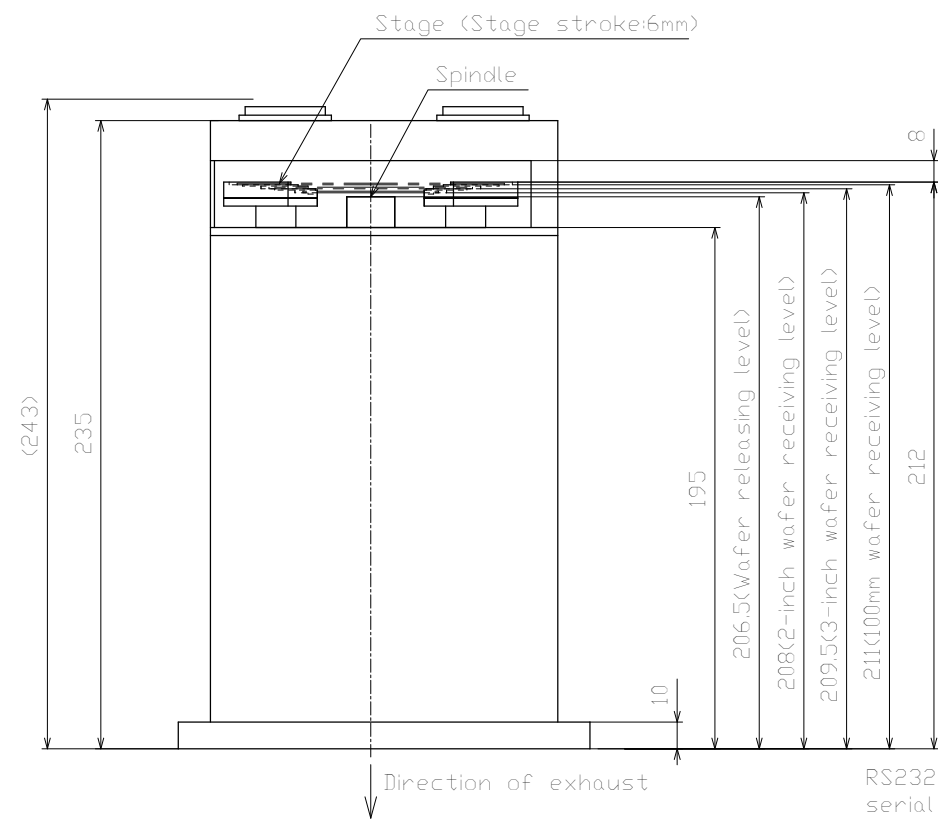


*Alignment movements
 Placing the wafer on stage
 ↓
 Closing the edge grip and positioning
 ↓
 Lowering the stage and adsorption
 ↓
 Opening the edge grip
 ↓
 Searching the orientation flat
 ↓
 Releasing suction to release the wafer

*After the wafer positioning, stage hands over the wafer to the spindle. (air is released)
 *Orientation flat detection sensor position is adjusted to detect the No.1 flat only. It might be necessary to adjust the sensor position depending on the flat length. Please contact JEL.



MODEL 型式	SAL2241		
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